

TECHNICAL DATA SHEET



Hi-Temp Purge Compound 478-45, 478-1000

Product Description

Hi-Temp Purge Compound solves the major problems of removing stubborn residues between color or resin changes. Hi-Temp Purge Compound is to be used as a continual purge with no soak time needed. Hi-Temp Purge Compound has a suggested temperature range, but please contact your Slide Technical Sales Representative for procedures at much higher temperatures or if a soak procedure is necessary.

Applications

Purging Compound

Unit Package Description

49 and 1100 pound boxes

Generic Description

Purging Compound

Net Weight Fill

45 & 1,000 pounds

UPC Code

858799000783

Appearance

Resin Pellet

Odor

None

Flash Point F

N/A

Flash Point C

N/A

Base Type

Resin

Evaporation Rate

N/A

HMIS Rating

0, 0, 0, None

DOT Proper Shipping Name

Not regulated, Granules, NOI

Removal

N/A

Units Per Case

45 & 1,000 pounds

Case Weight (lbs)

45 / 1,000

Working Temperature F

485 to 750 degrees

Working Temperature C

250 to 395 degrees

Propellant

N/A

NFPA Aerosol Flammability Level

N/A